

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|-------------------------|------------------|---------|------------------|
| L1 | 7 | (("6433285") or ("6591494") or ("6031724") or ("20020027274") or ("6076737") or ("6780668") or ("5866950")).PN. | US-PGPUB ; USPAT | OR | OFF | 2005/07/27 08:56 |
| L2 | 4194 | (chip ic semiconductor (integrated adj circuit)) with (resin plastic epox\$4) with (first one front upper top) with (second back reverse lower bottom) with (side\$1 surface\$1) | US-PGPUB ; USPAT; USOCR | OR | OFF | 2005/07/27 09:00 |
| L3 | 1186 | (chip ic semiconductor (integrated adj circuit)) with (resin plastic epox\$4) with (first one front upper top) with (second back reverse lower bottom) with (side\$1 surface\$1) with (board substrate pcb support\$3) with (contact\$3 terminal\$1 pad\$1 connect\$3) | US-PGPUB ; USPAT; USOCR | OR | OFF | 2005/07/27 09:02 |
| L4 | 546 | (chip ic semiconductor (integrated adj circuit)) with (resin plastic epox\$4) with (first one front upper top) with (second back reverse lower bottom) with (side\$1 surface\$1) with (board substrate pcb support\$3) with (contact\$3 terminal\$1 pad\$1 connect\$3) with (seal\$3 encapsulat\$3 encas\$3 mould\$3) | US-PGPUB ; USPAT; USOCR | OR | OFF | 2005/07/27 09:03 |
| L5 | 14 | (chip ic semiconductor (integrated adj circuit)) with (resin plastic epox\$4) with (first one front upper top) with (second back reverse lower bottom) with (side\$1 surface\$1) with (board substrate pcb support\$3) with (contact\$3 terminal\$1 pad\$1 connect\$3) with (seal\$3 encapsulat\$3 encas\$3 mould\$3) with (card\$1 tag\$1) | US-PGPUB ; USPAT; USOCR | OR | OFF | 2005/07/27 09:15 |

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|----|---|---|----------------------------|----|-----|------------------|
| L6 | 8 | (chip ic semiconductor (integrated adj circuit)) with (resin plastic epox\$4) with (first one front upper top) with (second back reverse lower bottom) with (side\$1 surface\$1) with (board substrate pcb support\$3) with (contact\$3 terminal\$1 pad\$1 connect\$3) with (seal\$3 encapsulat\$3 encas\$3 mould\$3) with (card\$1 tag\$1) | EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/27 09:16 |
|----|---|---|----------------------------|----|-----|------------------|